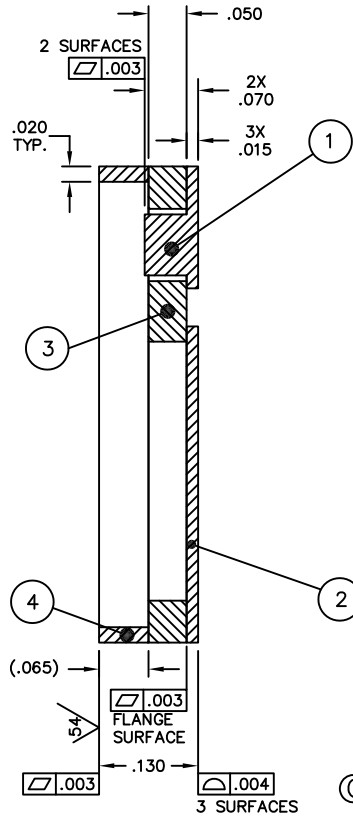
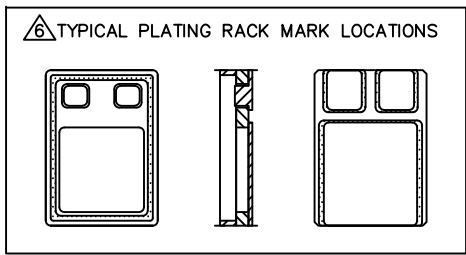
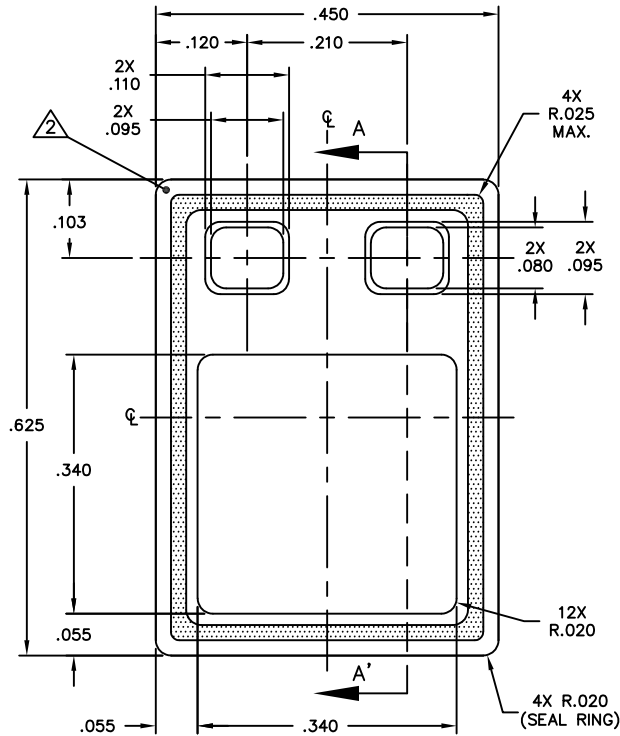
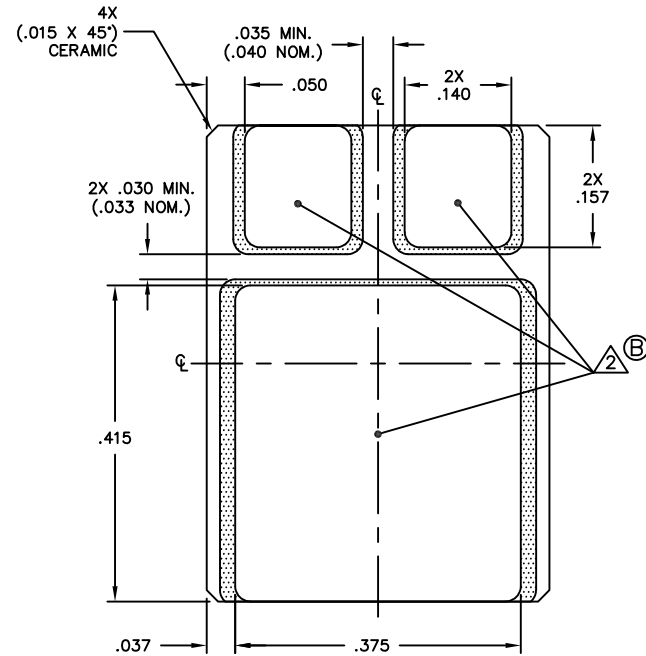


RELEASED 01-24-18

NO.	REVISIONS	BY/DATE	APPV. BY
B	CHANGED PLATING THICKNESS MEASUREMENT LOCATION PER ECN M102626	J.S. 11-23-15	E.S. 12-04-15
C	100-600 $\mu$ Ni WAS 100-350 $\mu$ PER ECN M103237.	J.S. 04-11-16	S.H. 05-06-16
D	ADDED NOTE 6 AND RACK MARK LOCATIONS PER ECN M105997.	J.S. 05-25-17	E.S. 01-22-18



SECTION A-A'



NOTES:

- ① METALLIZATION/PLATING: REFRACTORY METAL + ELECTROLYTIC Ni (100-600  $\mu$ ) + Au (50-150  $\mu$ ). GAP BETWEEN WCu PEDESTAL AND CERAMIC EXCLUDED FROM PLATING SPEC.
- ② MEASURE PLATING THICKNESS AT THESE 4 APPROXIMATE LOCATIONS USING XRF EQUIPMENT.
- 3. SEAL RING TO BE ELECTRICALLY ISOLATED FROM BONDING PADS.
- 4. HERMETICITY: LEAKAGE NOT TO EXCEED  $1.0 \times 10^{-8}$  atm cc/SEC He.
- 5. PLATING MUST WITHSTAND 420°C IN REDUCING ATMOSPHERE FOR 2 MINUTES WITHOUT BLISTERING OR FLAKING. DISCOLORATION ALLOWED PROVIDED THAT SURFACE DOES NOT IMPEDE SOLDERING OR WIRE BONDING.
- ⑥ PLATING RACK MARKS ARE BY DESIGN AND ALLOWED.

ITEM	DESCRIPTION	MATERIAL	REQ'D.	DRAWING NO.
4	SEAL RING	KOVAR (ASTM F-15)	1	15399
3	MEP CERAMIC	Al <sub>2</sub> O <sub>3</sub> 90% NOM.	1	15579-MEP
2	FLANGE	85%W/15%Cu	1	15590
1	FLANGE	85%W/15%Cu	2	15591

BILL OF MATERIALS

P001	AS SHOWN
PART NO.	DESCRIPTION

TOLERANCE UNLESS SPECIFIED .XX ± .01 .XXX ± .005 .XXXX ± ANGLES ± 5°	DRAWN BY <b>J.SERNA</b> DATE 07-24-15	COMPANY CONFIDENTIAL SAN DIEGO PLANT KYOCERA AMERICA INC. 8811 BALBOA AVENUE SAN DIEGO, CA 92123-1580	NAME FINAL ASSEMBLY
	CHECKED BY <b>C.NISWANDER</b> DATE 07-24-15		MATERIAL NOTED
DIMS. ARE IN INCHES DIMENSIONS AND TOLERANCES PER: ASME Y14.5M-1994	APPROVED BY <b>S.HIRA</b> DATE 07-27-15	PROJECT SMD-1.0	DWG. NO. SD-570-A2830
		REV. D	DR. N: SHEET 1 OF 1

